

## Phase Control Thyristors (Stud Version), 110 A



TO-209AC (TO-94)

### FEATURES

- Center gate
- International standard case TO-209AC (TO-94)
- Compression bonded encapsulation for heavy duty operations such as severe thermal cycling
- Hermetic glass-metal case with ceramic insulator (Glass-metal seal over 1200 V)
- Designed and qualified for industrial level
- Material categorization: For definitions of compliance please see [www.vishay.com/doc?99912](http://www.vishay.com/doc?99912)


**RoHS**  
COMPLIANT

### PRODUCT SUMMARY

$I_{T(AV)}$	110 A
$V_{DRM}/V_{RRM}$	400 V, 1600 V
$V_{TM}$	1.52 V
$I_{GT}$	150 mA
$T_J$	-40 °C to 140 °C
Package	TO-209AC (TO-94)
Diode variation	Single SCR

### TYPICAL APPLICATIONS

- DC motor controls
- Controlled DC power supplies
- AC controllers

### MAJOR RATINGS AND CHARACTERISTICS

PARAMETER	TEST CONDITIONS	VALUES	UNITS
$I_{T(AV)}$		110	A
	$T_C$	90	°C
$I_{T(RMS)}$		175	A
$I_{TSM}$	50 Hz	2700	
	60 Hz	2830	
$I^2t$	50 Hz	36.4	kA <sup>2</sup> s
	60 Hz	33.2	
$V_{DRM}/V_{RRM}$		400 to 1600	V
$t_q$	Typical	100	μs
$T_J$		-40 to 125	°C

### ELECTRICAL SPECIFICATIONS

#### VOLTAGE RATINGS

TYPE NUMBER	VOLTAGE CODE	$V_{DRM}/V_{RRM}$ , MAXIMUM REPETITIVE PEAK AND OFF-STATE VOLTAGE V	$V_{RSM}$ , MAXIMUM NON-REPETITIVE PEAK VOLTAGE V	$I_{DRM}/I_{RRM}$ MAXIMUM AT $T_J = T_J$ MAXIMUM mA
VS-ST110S	04	400	500	20
	08	800	900	
	12	1200	1300	
	16	1600	1700	



ABSOLUTE MAXIMUM RATINGS						
PARAMETER	SYMBOL	TEST CONDITIONS			VALUES	UNITS
Maximum average on-state current at case temperature	I <sub>T(AV)</sub>	180° conduction, half sine wave			110	A
					90	°C
Maximum RMS on-state current	I <sub>T(RMS)</sub>	DC at 85 °C case temperature			175	A
Maximum peak, one-cycle non-repetitive surge current	I <sub>TSM</sub>	t = 10 ms	No voltage reapplied	Sinusoidal half wave, initial T <sub>J</sub> = T <sub>J</sub> maximum	2700	
		t = 8.3 ms			2830	
		t = 10 ms	100 % V <sub>RRM</sub> reapplied		2270	
		t = 8.3 ms			2380	
Maximum I <sup>2</sup> t for fusing	I <sup>2</sup> t	t = 10 ms	No voltage reapplied		36.4	kA <sup>2</sup> s
		t = 8.3 ms			33.2	
		t = 10 ms	100 % V <sub>RRM</sub> reapplied		25.8	
		t = 8.3 ms			23.5	
Maximum I <sup>2</sup> √t for fusing	I <sup>2</sup> √t	t = 0.1 to 10 ms, no voltage reapplied			364	kA <sup>2</sup> √s
Low level value of threshold voltage	V <sub>T(TO)1</sub>	(16.7 % × π × I <sub>T(AV)</sub> < I < π × I <sub>T(AV)</sub> ), T <sub>J</sub> = T <sub>J</sub> maximum			0.90	V
High level value of threshold voltage	V <sub>T(TO)2</sub>	(I > π × I <sub>T(AV)</sub> ), T <sub>J</sub> = T <sub>J</sub> maximum			0.92	
Low level value of on-state slope resistance	r <sub>t1</sub>	(16.7 % × π × I <sub>T(AV)</sub> < I < π × I <sub>T(AV)</sub> ), T <sub>J</sub> = T <sub>J</sub> maximum			1.79	mΩ
High level value of on-state slope resistance	r <sub>t2</sub>	(I > π × I <sub>T(AV)</sub> ), T <sub>J</sub> = T <sub>J</sub> maximum			1.81	
Maximum on-state voltage	V <sub>TM</sub>	I <sub>pk</sub> = 350 A, T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> = 10 ms sine pulse			1.52	V
Maximum holding current	I <sub>H</sub>	T <sub>J</sub> = 25 °C, anode supply 12 V resistive load			600	mA
Typical latching current	I <sub>L</sub>				1000	

SWITCHING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum non-repetitive rate of rise of turned-on current	$di/dt$	Gate drive 20 V, 20 Ω, $t_r \leq 1$ μs $T_J = T_J$ maximum, anode voltage $\leq 80$ % $V_{DRM}$	500	A/μs
Typical delay time	$t_d$	Gate current 1 A, $di_g/dt = 1$ A/μs $V_d = 0.67$ % $V_{DRM}$ , $T_J = 25$ °C	2.0	μs
Typical turn-off time	$t_q$	$I_{TM} = 100$ A, $T_J = T_J$ maximum, $di/dt = 10$ A/μs, $V_R = 50$ V, $dV/dt = 20$ V/μs, gate 0 V 100 Ω, $t_p = 500$ μs	100	

BLOCKING				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum critical rate of rise of off-state voltage	$dV/dt$	$T_J = T_J$ maximum linear to 80 % rated $V_{DRM}$	500	V/μs
Maximum peak reverse and off-state leakage current	$I_{RRM}$ , $I_{DRM}$	$T_J = T_J$ maximum, rated $V_{DRM}/V_{RRM}$ applied	20	mA



TRIGGERING						
PARAMETER	SYMBOL	TEST CONDITIONS		VALUES		UNITS
				TYP.	MAX.	
Maximum peak gate power	P <sub>GM</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> ≤ 5 ms		5		W
Maximum average gate power	P <sub>G(AV)</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, f = 50 Hz, d% = 50		1		
Maximum peak positive gate current	I <sub>GM</sub>	T <sub>J</sub> = T <sub>J</sub> maximum, t <sub>p</sub> ≤ 5 ms		2.0		A
Maximum peak positive gate voltage	+ V <sub>GM</sub>			20		V
Maximum peak negative gate voltage	- V <sub>GM</sub>			5.0		
DC gate current required to trigger	I <sub>GT</sub>	T <sub>J</sub> = -40 °C	Maximum required gate trigger/ current/voltage are the lowest value which will trigger all units 6 V anode to cathode applied	180	-	mA
		T <sub>J</sub> = 25 °C		90	150	
		T <sub>J</sub> = 125 °C		40	-	
DC gate voltage required to trigger	V <sub>GT</sub>	T <sub>J</sub> = -40 °C		2.9	-	V
		T <sub>J</sub> = 25 °C		1.8	3.0	
		T <sub>J</sub> = 125 °C		1.2	-	
DC gate current not to trigger	I <sub>GD</sub>	T <sub>J</sub> = T <sub>J</sub> maximum	Maximum gate current/voltage not to trigger is the maximum value which will not trigger any unit with rated V <sub>DRM</sub> anode to cathode applied	10		mA
DC gate voltage not to trigger	V <sub>GD</sub>			0.25		V

THERMAL AND MECHANICAL SPECIFICATIONS				
PARAMETER	SYMBOL	TEST CONDITIONS	VALUES	UNITS
Maximum operating junction temperature range	$T_J$		-40 to 125	°C
Maximum storage temperature range	$T_{Stg}$		-40 to 150	
Maximum thermal resistance, junction to case	$R_{thJC}$	DC operation	0.195	K/W
Maximum thermal resistance, case to heatsink	$R_{thCS}$	Mounting surface, smooth, flat and greased	0.08	
Mounting torque, $\pm 10$ %		Non-lubricated threads	15.5 (137)	Nm (lbf · in)
		Lubricated threads	14 (120)	
Approximate weight			130	g
Case style		See dimensions - link at the end of datasheet	TO-209AC (TO-94)	

$\Delta R_{thJC}$ CONDUCTION				
CONDUCTION ANGLE	SINUSOIDAL CONDUCTION	RECTANGULAR CONDUCTION	TEST CONDITIONS	UNITS
180°	0.035	0.025	$T_J = T_J$ maximum	K/W
120°	0.041	0.042		
90°	0.052	0.056		
60°	0.076	0.079		
30°	0.126	0.127		

**Note**

- The table above shows the increment of thermal resistance  $R_{thJC}$  when devices operate at different conduction angles than DC

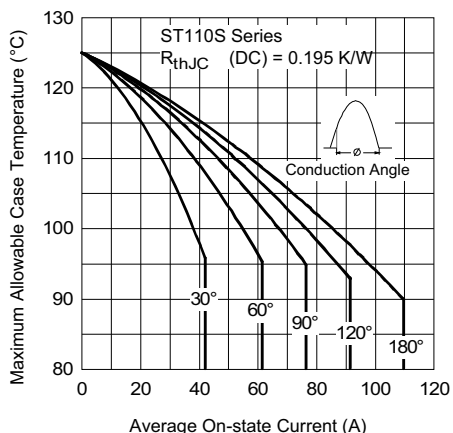


Fig. 1 - Current Ratings Characteristics

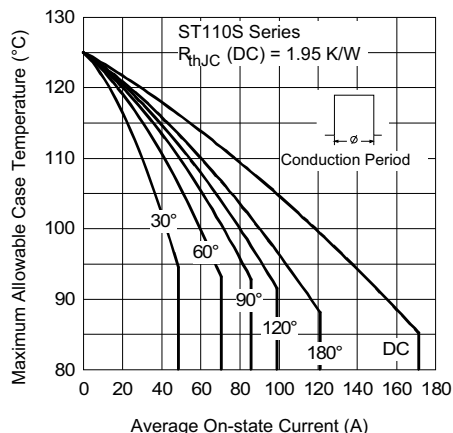


Fig. 2 - Current Ratings Characteristics

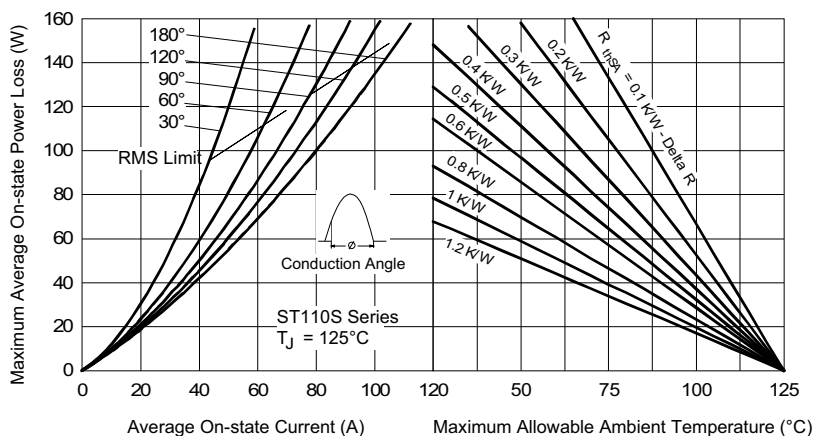


Fig. 3 - On-State Power Loss Characteristics

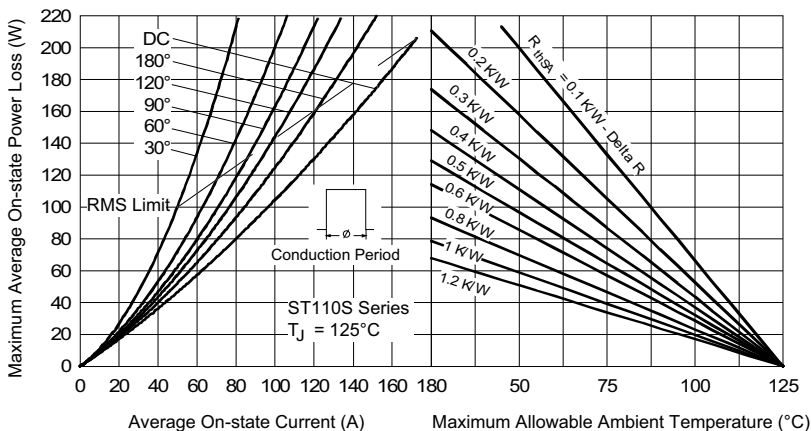


Fig. 4 - On-State Power Loss Characteristics

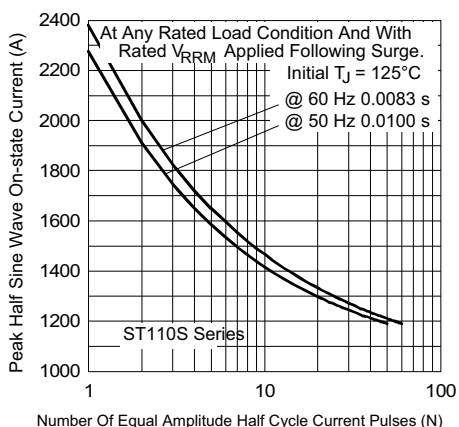


Fig. 5 - Maximum Non-Repetitive Surge Current

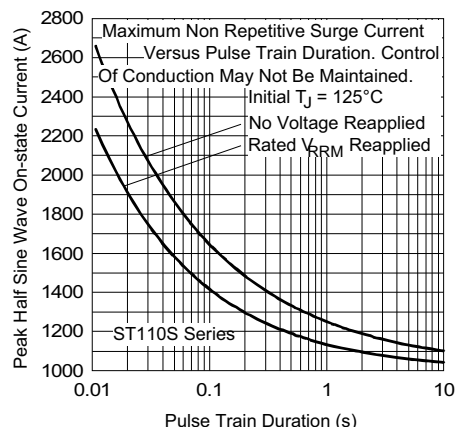


Fig. 6 - Maximum Non-Repetitive Surge Current

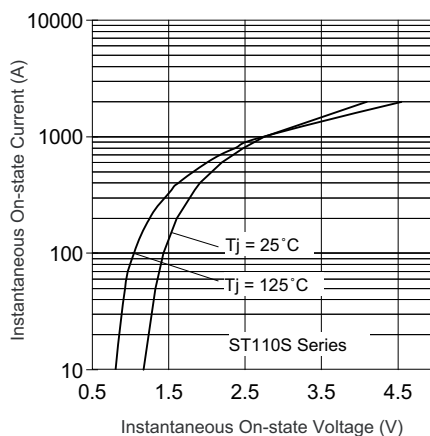


Fig. 7 - On-State Voltage Drop Characteristics

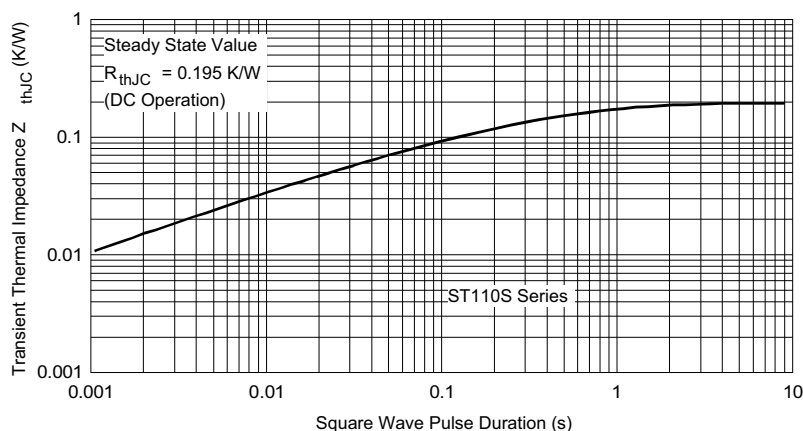


Fig. 8 - Thermal Impedance  $Z_{thJC}$  Characteristic

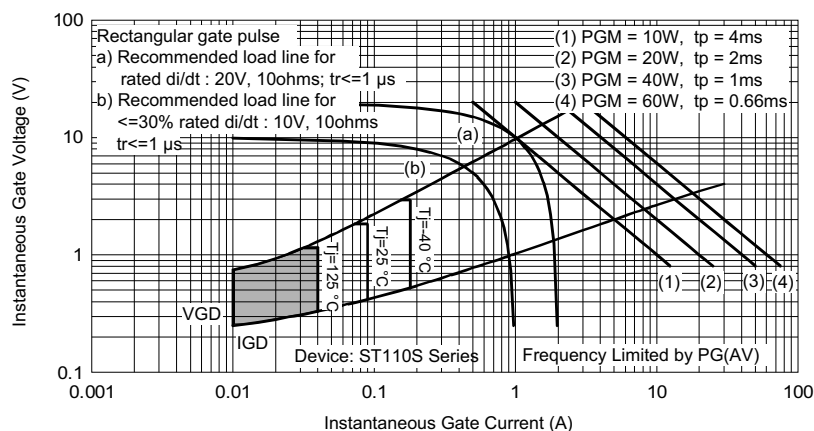


Fig. 9 - Gate Characteristics

## ORDERING INFORMATION TABLE

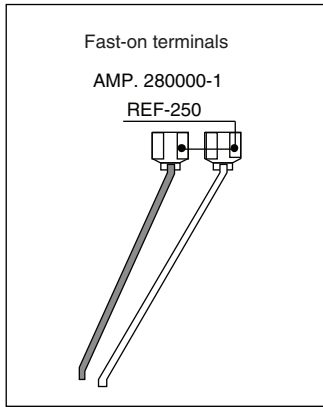
Device code	VS-	ST	11	0	S	16	P	0	V	L	PbF
	(1)	(2)	(3)	(4)	(5)	(6)	(7)	(8)	(9)	(10)	(11)

- 1** - Vishay Semiconductors product
- 2** - Thyristor
- 3** - Essential part marking
- 4** - 0 = Converter grade
- 5** - S = Compression bonding stud
- 6** - Voltage code  $\times 100 = V_{RRM}$  (see Voltage Ratings table)
- 7** - P = Stud base 20UNF threads
- 8** - 0 = Eyelet terminals (gate and auxiliary cathode leads)  
1 = Fast-on terminals (gate and auxiliary cathode leads)  
2 = Flag terminals (for cathode and gate terminals)
- 9** - • V = Glass-metal seal (only up to 1200 V)  
• None = Ceramic housing (over 1200 V)
- 10** - Critical  $dV/dt$ :  
• None = 500 V/ $\mu s$  (standard value)  
• L = 1000 V/ $\mu s$  (special selection)
- 11** - None = Standard production  
PbF = Lead (Pb)-free

## LINKS TO RELATED DOCUMENTS

Dimensions	<a href="http://www.vishay.com/doc?95078">www.vishay.com/doc?95078</a>
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**DIMENSIONS** in millimeters (inches)

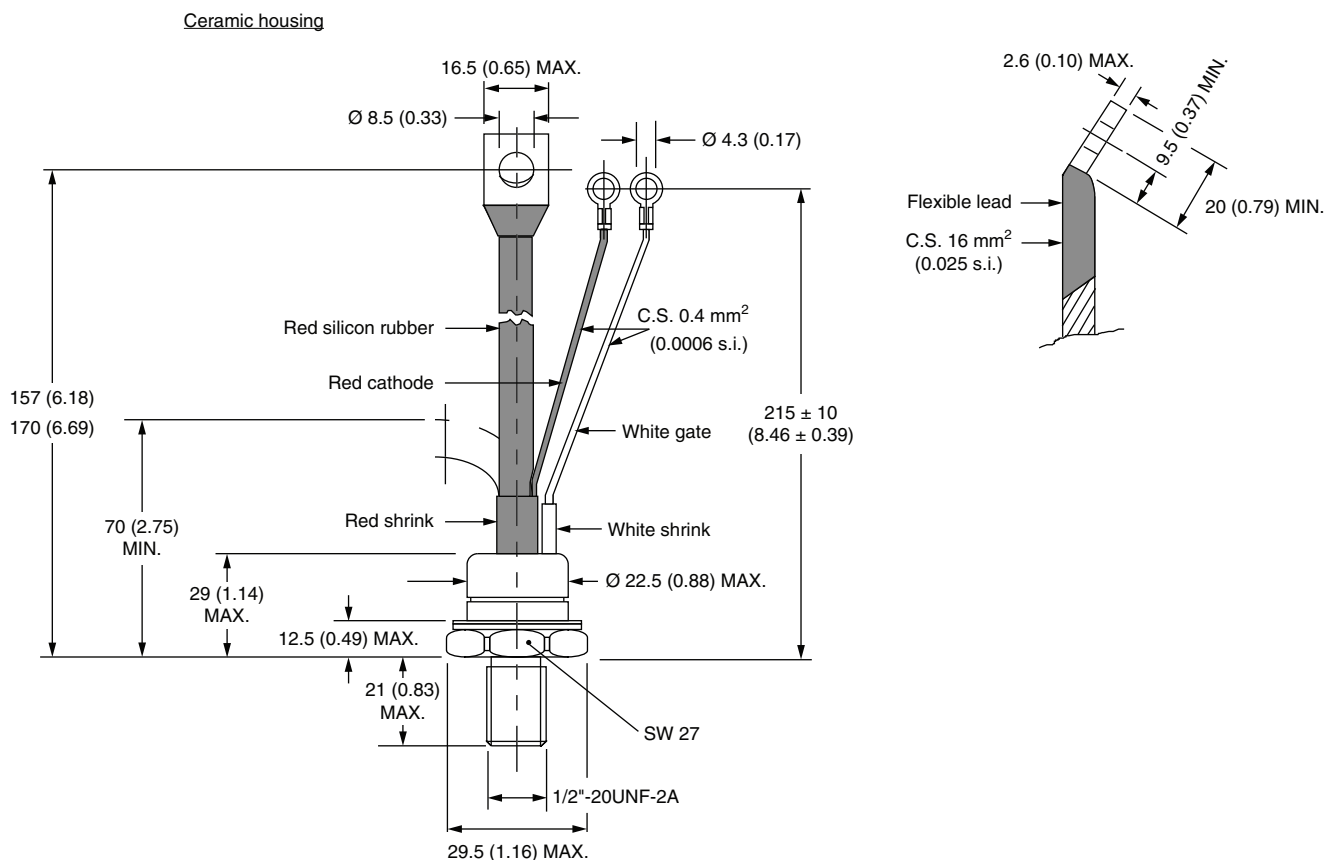


# Outline Dimensions

Vishay Semiconductors TO-209AC (TO-94) for ST110S Series



**DIMENSIONS** in millimeters (inches)







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